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COOL-BOND
ME7635-RC

High Strength
Rapid Curing
100% Solid
Insulating
Epoxy Paste Adhesive

IDEAL FOR:

Rapid to Snap Curing
 Die-Attach
 Automated Assembly

DESCRIPTION:

ME7635-RC is an thermally conductive insulating epoxy adhesive for die-attach applications. This thixotropic paste is solvent free. (TI is approx. 3.0). It is designed for automated, inline bonding processing.

ME7635-RC is low in ionic impurities (<60 ppm total) and meets all requirements for MIL-Std 883D 5011.4 specification for dielectric adhesive. Fast curing can be achieved from 80°C and higher temperatures.

AVAILABILITY:

ME7635-RC is available in syringes for automatic needle dispense applications or in jars.

APPLICATION PROCEDURES:

- (1) Thaw for 30 minutes before opening jar or using syringes.
- (2) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- (3) Cure according to one of the recommended schedules.

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 2 min)	>1x10 ¹⁴ ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	60 ±10%
Current Carrying Capabilities	
Lap-Shear Strength	>1500 psi >10.3 N/mm ²
Device Push-off Strength	>3200 psi >22.0 N/mm ²
Hardness (Type)	80 (D) ±10%
Cured Density (gm/cc)	1.9 ±10%
Thermal Conductivity	9 Btu-in/hr-ft ² -°F ±10% 1.2 W/m-°C ±10%
Linear Thermal Expansion	40 ±15%
Coeff. (ppm/°C)	
Maximum Continuous Operation Temp. (°C)	<150
Pot Life	5 day at 25°C
Avg. Viscosity(5 rpm, 24°C) (Brookfield DV-1,spindle CP51)	38,000 cp ±20%
Thixotropic Index	2.5

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
80°C	30 min	
100°C	15 min	
125°C	6 min	
150°C	3 min	

Bond strength at 150C for 2 hours is the same as 3 min.

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr
25°C	1 mo

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

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